



# APPROVAL SHEET

Approval Specification	Customer's Approval Certificate
<b>TO:</b>  <b>Part No.:</b>  <b>Customer's Part No.:</b>	Please return this copy as a certification of your approval  <b>Checked &amp; Approved by:</b>  <b>Date:</b>

## BEIJING ZHONGXUN SIFANG SCIENCE & TECHNOLOGY CO.,LTD.

Tel: +86-010-58937383  
 Fax: +86-010-58937263  
 E-mail: [bjzxsf@bjzxsf.net](mailto:bjzxsf@bjzxsf.net)  
 Website: <http://www.bjzxsf.net>  
 Add: No 201, Block A. Building 3. Yongjie Beilu  
 Yongfeng high-tech industrial base  
 Haidian District Beijing city



Part No.	:	SF1549
Pages	:	6
Date	:	2015/9/2
Revision	:	1.1

<b>Prepared by:</b>	梁浩
<b>Checked by:</b>	
<b>Approved by:</b>	

**Application**

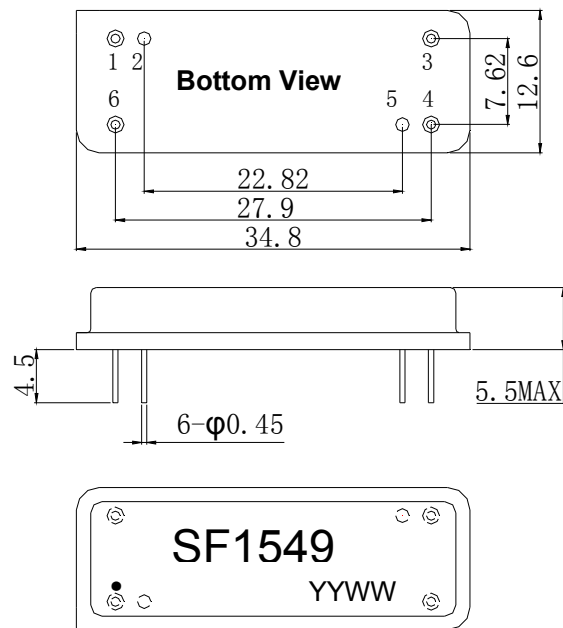
- High-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Passband 17.46 MHz
- Low Shape factor



**Features**

- RoHS compatible
- Package size 34.8x12.6x5.50mm<sup>3</sup>
- Package Code DIP3512
- Electrostatic Sensitive Device(ESD)

**Package Dimensions (Unit: mm)**



**Pin Configuration**

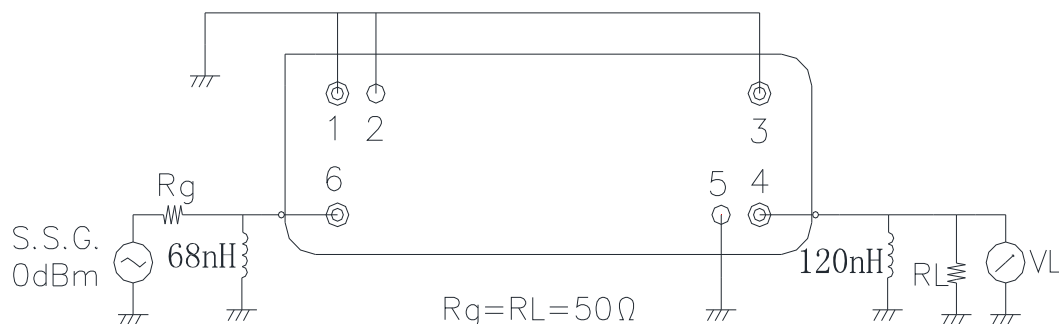
Pin No.	Description
6	Input
4	Output
1,2,3,5	Ground

**Marking Description**

<b>S</b>	Trademark
<b>F</b>	SAW Filter
<b>1549</b>	Part Number
<b>●</b>	Pin 1
<b>YYWW</b>	Year Code & Week Code

\*Fig: If the products produced in 06<sup>th</sup> week of 2012, The year code & week code is 1206.

**Test Circuit(Bottom View)**



**Performance****Maximum Rating**

Item		Value	Unit
DC Voltage	$V_{DC}$	3	V
Operation Temperature	T	-40 ~ +85	°C
Storage Temperature	$T_{stg}$	-55 ~ +125	°C
RF Power Dissipation	P	10	dBm

**Electronic Characteristics**

Test Temperature:  $25^{\circ}\text{C} \pm 2^{\circ}\text{C}$

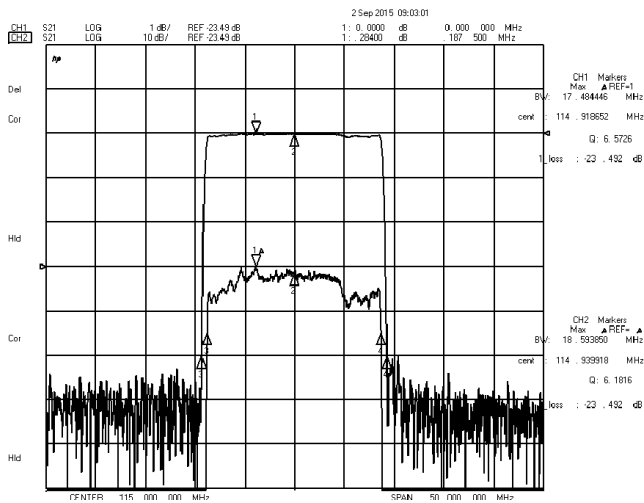
Terminating source impedance:  $50\Omega$

Terminating load impedance:  $50\Omega$

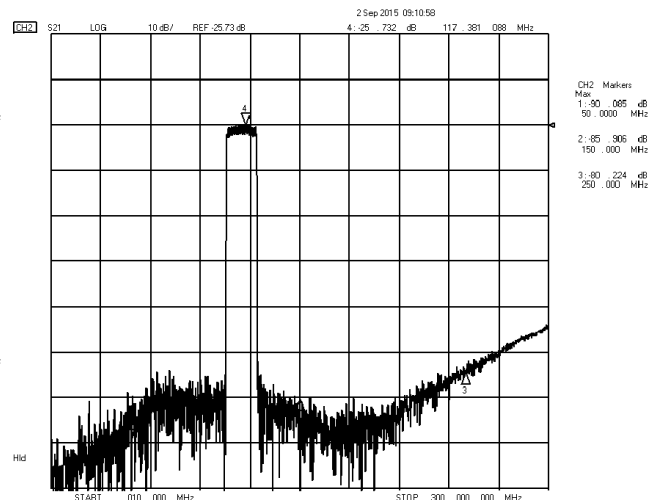
Item		Minimum	Typical	Maximum	Unit
Center Frequency	$f_c$	114.9	115.0	115.1	MHz
Insertion Loss(min)	IL		24.0	28.0	dB
Amplitude Ripple	$\Delta\alpha$		1.0	1.5	dB
1.5 dB Bandwidth	$BW_{1.5dB}$	17.46	17.48		MHz
40 dB Bandwidth	$BW_{40dB}$		18.56	18.60	MHz
50 dB Bandwidth	$BW_{50dB}$		18.6	19.4	MHz
Absolute Delay	AD		3.4	4.0	us
Phase Linearity	107.10-122.90MHz		10.0	12.0	deg
Absolute Attenuation	$\alpha$	50.0	52.0		dB

### Frequency Characteristics

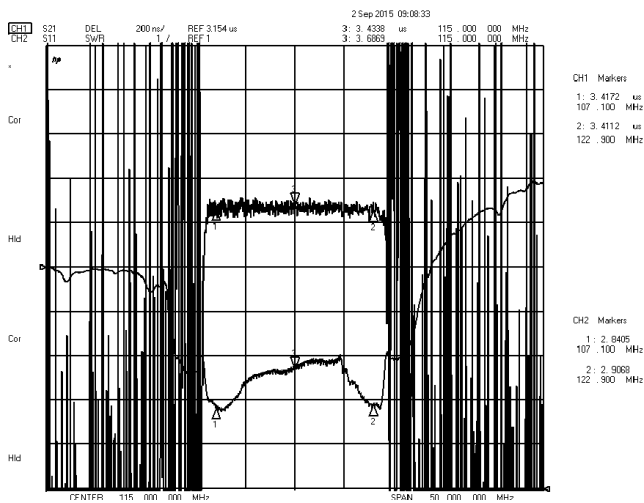
#### Frequency Response



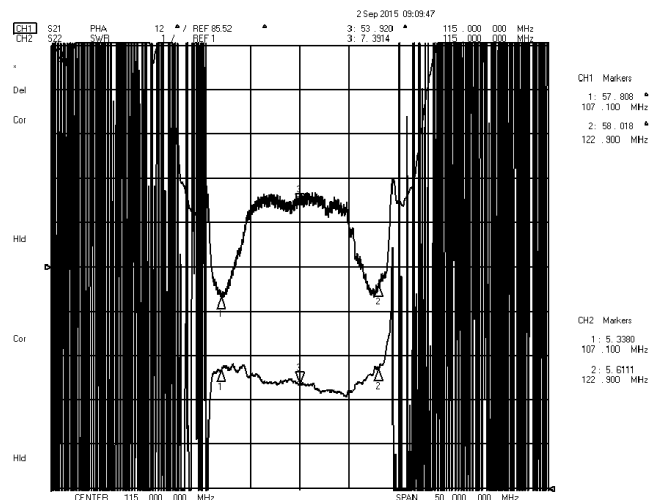
#### Frequency Response (wideband)



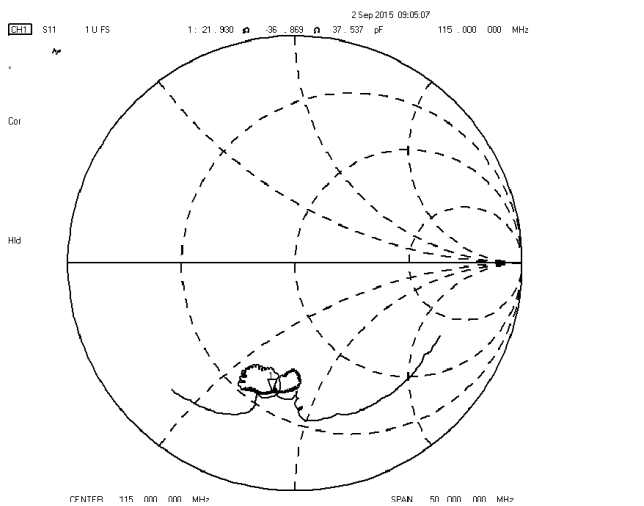
#### Delay Ripple & S11 VSWR



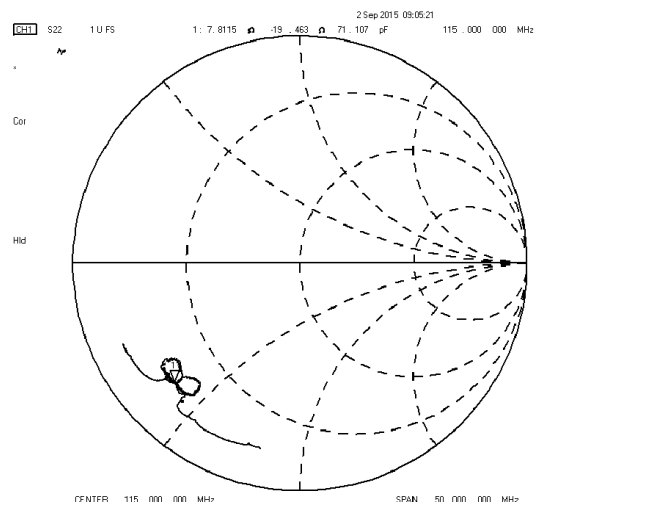
#### Phase Linearity & S22 VSWR



#### S11 Smith Chart

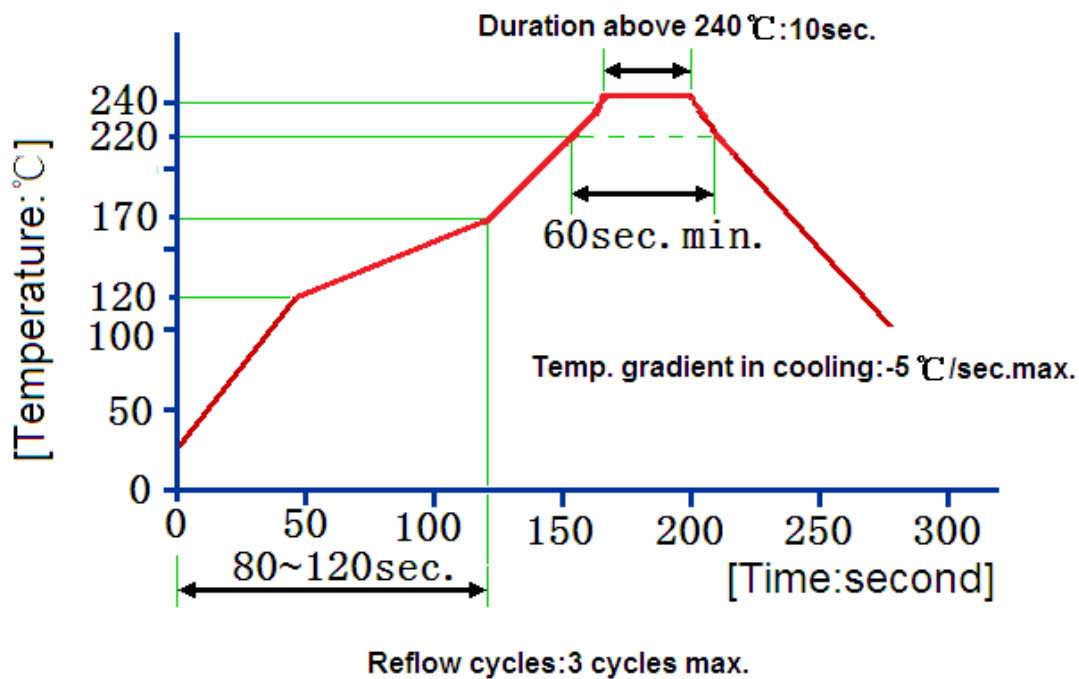


#### S22 Smith Chart



**Reliability (The SAW components shall remain electrical performance after tests)**

No.	Test item	Test condition
1	Temperature Storage	(1) Temperature: 85°C±2°C , Duration: 250h , Recovery time: 2h±0.5h (2) Temperature: -55°C±3°C , Duration: 250h , Recovery time: 2h±0.5h
2	Humidity Test	Conditions: 60°C±2°C , 90~95% RH                                  Duration: 250h
3	Thermal Shock	Heat cycle conditions: TA=-55°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.
4	Vibration Fatigue	Frequency of vibration: 10~55Hz                                  Amplitude: 1.5mm Directions: X, Y and Z    Duration: 2h
5	Drop Test	Cycle time: 10 times    Height: 1.0m
6	Solder Ability Test	Temperature: 245°C±5°C    Duration: 3.0s~5.0s Depth: DIP--2/3 , SMD--1/5
7	Resistance to Soldering Heat	(1) Thickness of PCB: 1mm , Solder condition: 260°C±5°C , Duration: 10±1s (2) Temperature of Soldering Iron: 350°C±10°C , Duration: 3~4s , Recovery time : 2 ± 0.5h

**Recommended Reflow Soldering Diagram**

**Notes**

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.